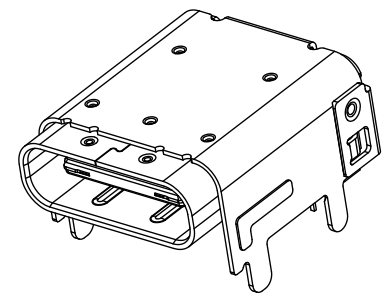
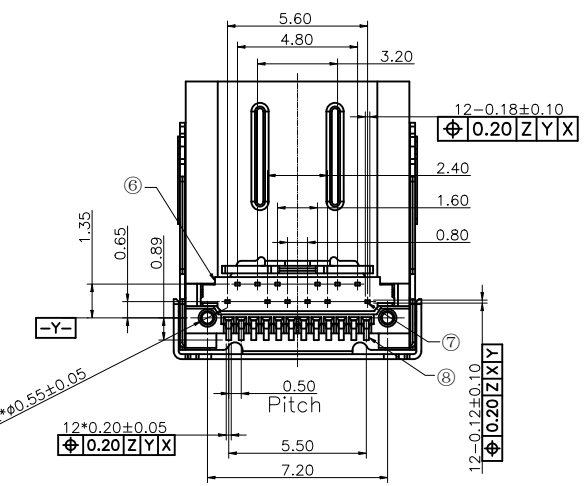
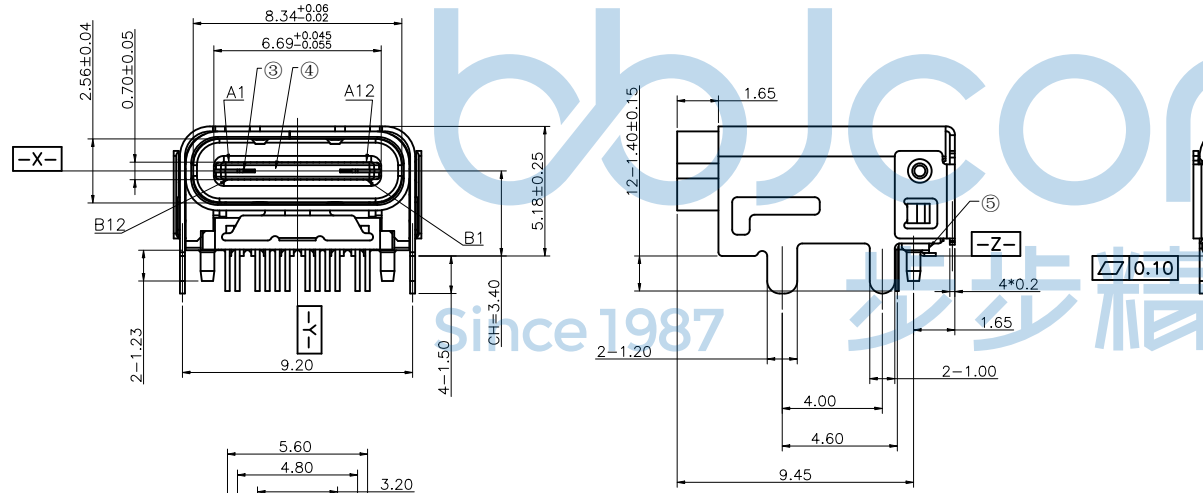
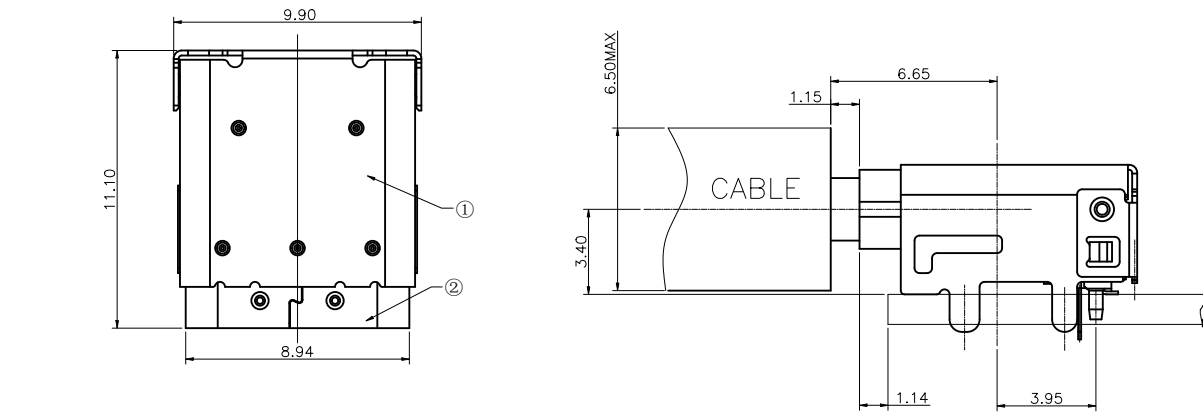


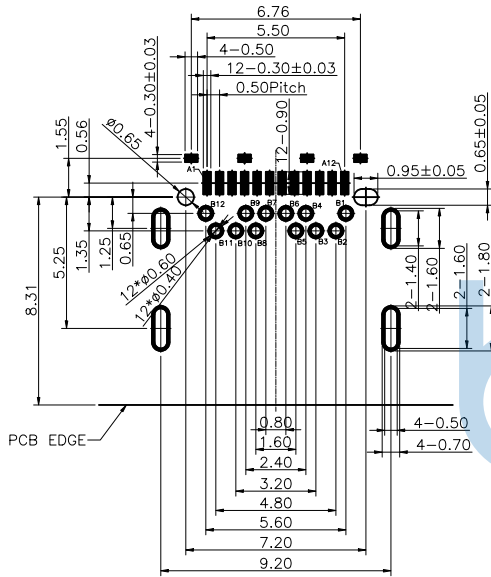
REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP



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APPD.	JM_Zheng	PJ. NO.: 126-223-240028-T7G SIZE: A4 DRW NO.:		FINISH: SEE NOTES MAT'L.: SEE NOTES	
CHKD.	LYX	SCALE: N/A		REV.: A0	UNIT: mm
PDWG.NO:	0228-1	DR.	TSP	PAGE: 1/3	

USB TYPE-C FULL-FEATURED RECEPTACLE INTERFACE PIN ASSIGNMENTS

REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP



RECOMMENDED PCB LAYOUT (COMPONENT SIDE)

PCB THICKNESS: 1.60±0.05
DEFAULT TOLERANCE: ±0.05

PIN	Signal Name	Description	PIN	Signal Name	Description
A1	GND	Ground return	B12	GND	Ground return
A2	SSTXp1	Positive half of first SuperSpeed TX differential pair	B11	SSRXp1	Negative half of first SuperSpeed RX differential pair
A3	SSTXn1	Negative half of first SuperSpeed TX differential pair	B10	SSRXn1	Positive half of first SuperSpeed RX differential pair
A4	VBUS	Bus Power	B9	VBUS	Bus Power
A5	CC1	Configuration Channel	B8	SBU2	Sideband Use (SBU)
A6	Dp1	Positive half of the USB 2.0 differential pair-Position 1	B7	Dn2	Negative half of the USB 2.0 differential pair-Position 2
A7	Dn1	Negative half of the USB 2.0 differential pair-Position 1	B6	Dp2	Positive half of the USB 2.0 differential pair-Position 2
A8	SBU1	Sideband Use (SBU)	B5	CC2	Configuration Channel
A9	VBUS	Bus Power	B4	VBUS	Bus Power
A10	SSRXn2	Negative half of second SuperSpeed RX differential pair	B3	SSTXn2	Negative half of second SuperSpeed TX differential pair
A11	SSRXp2	Positive half of second SuperSpeed RX differential pair	B2	SSTXp2	Positive half of second SuperSpeed TX differential pair
A12	GND	Ground return	B1	GND	Ground return

1.MATERIAL:
MOLDING: LCP UL94 V-0
CONTACT: COPPER ALLOY.
GOLD PLATED ON CONTACT AREA, 100u"
Min TIN (LEAD FREE) ON SOLDER AREA,
SHELL: SUS 304-1/2H, T=0.30±0.03mm
50u" NICKEL PLATING OVER ALL.

2.MECHANICAL:
INSERTION: 5~20N.
EXTRACTION: 6~20N.
DURABILITY: 10000 CYCLES

3.ELECTRICAL:
CURRENT: 5A MAX FOR VBUS;
1.25A FOR GND, 0.25A FOR OTHER.
VOLTAGE: 20VDC MAX
WITHSTANDING VOLTAGE: 100V AC.
CONTACT RESISTANCE: 40mΩ MAX.
INSULATION RESISTANCE: 100MΩ MIN.

4.ENVIRONMENTAL
TEMPERATURE RANGE -55°C ~ +85°C



8	UPPER CONTACT	12	COPPER ALLOY	Ni 50u" Min AT TAIL, 1U" Min Au AT SOLDER AU G/F Min AT CONNECT AREA Ni 80u" Min.
7	LOWER CONTACT	12		
6	LOWER IM	1	THERMOPLASTIC UL 94V-0	COLOR: LCP BLACK
5	UPPER IM	1	THERMOPLASTIC UL 94V-0	COLOR: LCP BLACK
4	OVERMOLD	1	THERMOPLASTIC UL 94V-0	COLOR: LCP BLACK
3	SHIELD PLATE	1	STAINLESS STEEL	NICKEL PLATING AT OVER ALL
2	INNER SHELL	1	STAINLESS STEEL	CLEAN
1	OUTER SHELL	1	STAINLESS STEEL	NICKEL PLATING ONLY AT TAIL, AU AT SOLDER TAIL
NO.	DESCRIPTION	QTY	MATERIAL	SPECIFICATION

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PDWG. NO: 0228-1

深圳市步步精科技有限公司

NAME: TYPE-C 24P 母座 板上四脚插 带柱 外壳脚长1.5
双壳 端子SMT+DIP L=11.10 CH=3.40

PJ. NO.: 126-223-240028-T7G
SIZE: A4 | DRW NO.:

FINISH: SEE NOTES | MAT'L.: SEE NOTES
SCALE: N/A | REV.: A0 | UNIT: mm | PAGE: 2/3

